

280384-1 ✓ ACTIVE

AMPMODU | AMPMODU Headers

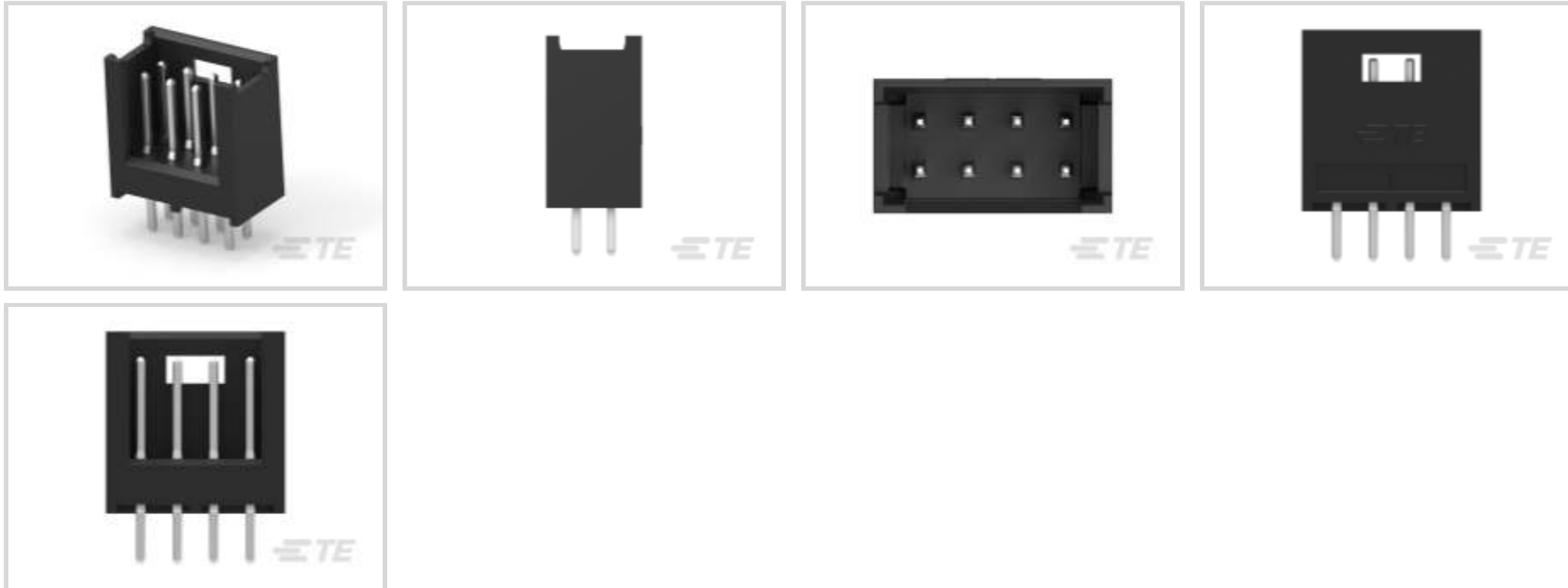
TE Internal #: 280384-1

PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **8**

Number of Rows: **2**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type | PCB Mount Header |
| Connector System | Board-to-Board |
| Header Type | Partially Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Vertical |
| Number of Positions | 8 |
| Number of Rows | 2 |

Electrical Characteristics

| | |
|---------------------------------------|-------|
| Dielectric Withstanding Voltage (Max) | 750 V |
|---------------------------------------|-------|

Body Features

| | |
|-------------------|----------|
| Connector Profile | Standard |
|-------------------|----------|



| | |
|-----------------------|-------|
| Primary Product Color | Black |
|-----------------------|-------|

Contact Features

| | |
|---|-------------|
| PCB Contact Termination Area Plating Material Thickness | 3.5 μ m |
|---|-------------|

| | |
|----------------------|-------|
| Contact Shape & Form | Round |
|----------------------|-------|

| | |
|---|--------|
| Contact Mating Area Plating Material Finish | Bright |
|---|--------|

| | |
|---|-----|
| PCB Contact Termination Area Plating Material | Tin |
|---|-----|

| | |
|-----------------------|-----------------|
| Contact Base Material | Phosphor Bronze |
|-----------------------|-----------------|

| | |
|--------------------------------------|-----|
| Contact Mating Area Plating Material | Tin |
|--------------------------------------|-----|

| | |
|--------------|-----|
| Contact Type | Pin |
|--------------|-----|

Termination Features

| | |
|--------------------------------|------------------|
| Termination Post & Tail Length | 3.5 mm [.138 in] |
|--------------------------------|------------------|

| | |
|---|-----------------------|
| Termination Method to Printed Circuit Board | Through Hole - Solder |
|---|-----------------------|

Mechanical Attachment

| | |
|------------------|------|
| Mating Retention | With |
|------------------|------|

| | |
|---------------------|---------|
| Panel Mount Feature | Without |
|---------------------|---------|

| | |
|------------------|------|
| Mating Alignment | With |
|------------------|------|

| | |
|-----------------------|--------------|
| Mating Alignment Type | Polarization |
|-----------------------|--------------|

| | |
|---------------------|---------|
| PCB Mount Retention | Without |
|---------------------|---------|

| | |
|---------------------|---------|
| PCB Mount Alignment | Without |
|---------------------|---------|

| | |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

Housing Features

| | |
|--------------------|-----------------|
| Centerline (Pitch) | 2.54 mm [.1 in] |
|--------------------|-----------------|

| | |
|------------------|---------------|
| Housing Material | Thermoplastic |
|------------------|---------------|

Dimensions

| | |
|--------------------|-----------------|
| Row-to-Row Spacing | 2.54 mm [.1 in] |
|--------------------|-----------------|

Usage Conditions

| | |
|----------------------------|----------|
| Housing Temperature Rating | Standard |
|----------------------------|----------|

| | |
|-----------------------------|-----------------------------|
| Operating Temperature Range | -65 – 105 °C [-85 – 221 °F] |
|-----------------------------|-----------------------------|

Operation/Application

| | |
|---------------------|----------------|
| Circuit Application | Power & Signal |
|---------------------|----------------|

Packaging Features

| | |
|--------------------|------|
| Packaging Quantity | 1000 |
|--------------------|------|

| | |
|----------------|-----|
| Packaging Type | Box |
|----------------|-----|

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|------------------------------|-----------|
| EU RoHS Directive 2011/65/EU | Compliant |
|------------------------------|-----------|

| | |
|-----------------------------|-----------|
| EU ELV Directive 2000/53/EC | Compliant |
|-----------------------------|-----------|

| | |
|---|---|
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
|---|---|

| | |
|--|---|
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
|--|---|

| | |
|-----------------|--|
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
|-----------------|--|

| | |
|---------------------------|------------------------------|
| Solder Process Capability | Wave solder capable to 265°C |
|---------------------------|------------------------------|

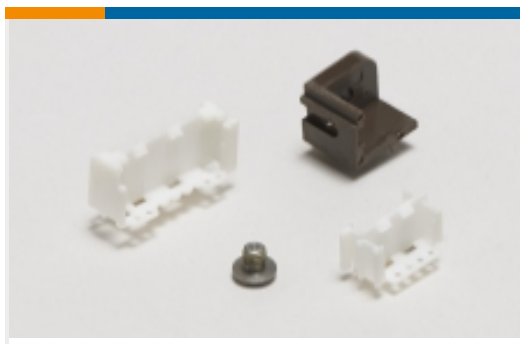
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



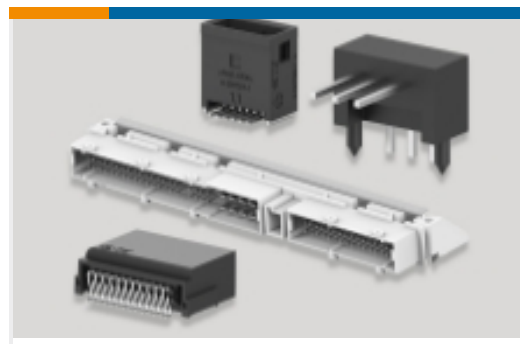
Also in the Series | [AMPMODU Headers](#)



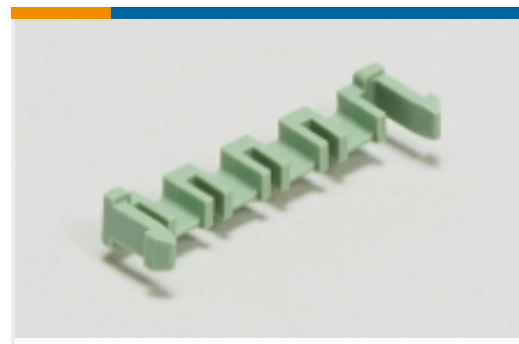
PCB Connector Mounting(1)



PCB Connector Shrouds(1)



PCB Headers & Receptacles(4875)



PCB Latches, Locks & Retainers(1)



Wire-to-Board Connector Assemblies & Housings(5)



Wire-to-Board Connector Contacts(65)

Customers Also Bought



TE Part #1625971-3
HSA25 10K 5%



TE Part #3-1879071-7
THS50 75R 5%



TE Part #280373-1
8P AMPMODU II SHRD HDR, ST, TIN



TE Part #280370-1
2P AMPMODU II SHRD HDR, ST, TIN



TE Part #3-1879134-3
RN 0603 21K5 0.1% 10PPM 1K RL



TE Part #280389-1
2X4P MODU II SHRD HDR, RT ANG, TIN



TE Part #7-1879417-0
CPF0603 634K 0.1% 25PPM 1K RL

Documents

Product Drawings

[2X4P AMPMODU II SHRD HDR, ST, TIN](#)

English

CAD Files

[3D PDF](#)

[3D](#)

[Customer View Model](#)

[ENG_CVM_CVM_280384-1_T_c-280384-1-t.2d_dxf.zip](#)



English

Customer View Model

[ENG_CVM_CVM_280384-1_T_c-280384-1-t.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_280384-1_T_c-280384-1-t.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[1773393_AMPMODU_EUROPEAN_STANDARD_PRODUCTS](#)

English

Product Environmental Compliance

[Product Compliance](#)

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